



PC BOARD LAYOUT

Note:

- 1.Material:  
 1.1 Insulator: High temperature thermoplastic with g.f,UL94v-0  
 1.2 Contact: Copper alloy,t=0.20mm  
 1.3 Shell: Spcc,t=0.30mm
- 2.Specification:  
 2.1 Current rating: 1 A Max.  
 2.2 Dielectric withstanding voltage: 750 V(ac) for 1 min.  
 2.3 Contact resistance: 30 mW Max.  
 2.4 Insulation resistance: 1000 MW Min.  
 2.5 Total mating force: 7.0 Kgf Max.  
 2.6 Total unmating force: 1.5 Kgf Min.  
 2.7 Temperature range: -55°C~85°C

DD-SG-xx-LF  
 LEADFREE

RoHS Compliant

PART NO	A±0.25	B±0.20	C±0.20	D±0.20	E±0.30	F±0.25	G±0.25	H±0.05	I±0.10	J±0.25	K±0.25
DD-SG-09	30.81	24.99	16.33	7.9	16.8		12.55	2.77	2.84		
DD-SG-15	39.25	33.32	24.66	7.9	16.8		12.55	2.77	2.84		
DD-SG-19	44.80	38.86	30.0	7.9	16.8		12.55	2.77	2.84		
DD-SG-23	50.30	44.3	35.3	7.9	16.8		12.55	2.77	2.84		
DD-SG-25	53.04	47.04	38.38	7.9	16.8		12.55	2.77	2.84		
DD-SG-37	69.50	63.50	54.84	7.9	16.8		12.55	2.77	2.84		



PART NO. DD-SG-xx

DWG NO. DD-SG-xx

FILE NO.

APPROVED BY CY

DRAWING BY

TOLERANCES ARE  
 .X ± 0.3  
 .XX ± 0.2  
 .XXX ± 0.1  
 AWG

DESCRIPTION: D-SUB DIP 180°

煜倫股份有限公司

UNIT / mm

SCALE 1:1

PROJECTION

AREA

REVISIONS

HK

DATE